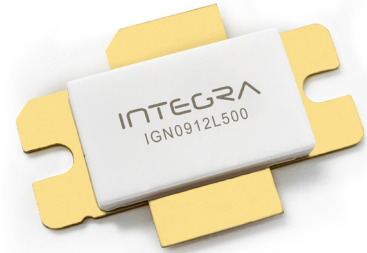


# L-Band, GaN/SiC, RF Power Transistor

960-1220 MHz | 500 W | 65% Efficiency typ | 16.5 dB Gain typ | 50 V | Link 16

IGN0912L500 is a high power GaN-on-SiC RF power transistors that has been designed to suit the needs of IFF/SSR avionics systems, military tactical data links, and TACAN/DME systems. It operates over the full instantaneous bandwidth of 960-1220MHz. Under Link 16 [444x (7µs on, 6µs off), 22.7% Long Term Duty Cycle] pulse conditions it supplies a minimum of 500 W of peak output power, with typically 16.5 dB of gain and 65% efficiency. It operates from a 50 V supply voltage. For optimal thermal efficiency, the transistor is housed in a metal-based package with an epoxy-sealed ceramic lid.

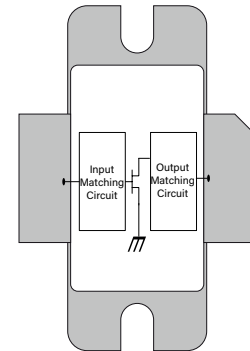


## FEATURES

- GaN on SiC HEMT Technology
- Output Power >500 W
- Pre-matched Input and Output Impedance
- High Efficiency - 65% typical
- 100% RF Tested Under Link 16 pulse conditions
- RoHS and REACH Compliant

## APPLICATIONS

- Link 16 applications
- TACAN/DME Systems



**Table 1. Absolute Maximum Ratings (Not Simultaneous)**

Parameter	Symbol	Value	Units	Test Conditions
DC Drain-Source Voltage	$V_{DS}$	160	V	25 °C
DC Gate-Source Voltage	$V_{GS}$	-8 to +1	V	25 °C
DC Drain Current	$I_D$	48	A	25 °C
DC Gate Current	$I_G$	4.8	mA	25 °C
RF Input Power	$P_{RF,IN}$	16	W	25 °C
Operating Channel Temperature	$T_{CH}$	-55 to +225	°C	
Storage Temperature	$T_{STG}$	-55 to +150	°C	
Soldering Temperature	$T_{SOLDER}$	260 for 60s	°C	

Note: Operation outside the limits given in this table may cause permanent damage to the transistor

**Table 2. DC Electrical Characteristics (Case temperature = 25 °C unless otherwise stated)**

Parameter	Symbol	Min	Typ	Max	Units	Test Conditions
Gate Pinch-Off Voltage	$V_P$	-5			V	$V_{DS} = 50V, I_{DS} = 1mA$
Quiescent Gate Voltage	$V_Q$		-2.8		V	$V_{DS} = 50V, I_{DS} = 100mA$

**Table 3. RF Electrical Characteristics (Case temperature = 30 °C unless otherwise stated)**

Parameter	Symbol	Min	Typ	Max	Units	Test Conditions
RF Input Power	$P_{IN,RF}$	7.9	11.2	15.8	W	$P_{OUT} = 500W$ $f = 960, 1090, 1220 \text{ MHz}$ $V_{DS} = 50V, I_{DS} = 100mA$ Link 16 pulse conditions (444 x [7µs on, 6µs off], LTDC = 22.7%)
Gain	G	15	16.5	18	dB	
Drain Efficiency	$\eta$	60	65	75	%	
Input Return Loss	IRL	7	12	20	dB	
Pulse Droop	D	-0.5	-0.2	+0.2	dB	
Load Mismatch Stability	VSWR-S	2:1				
VSWR Withstand	VSWR-LMT	3:1				

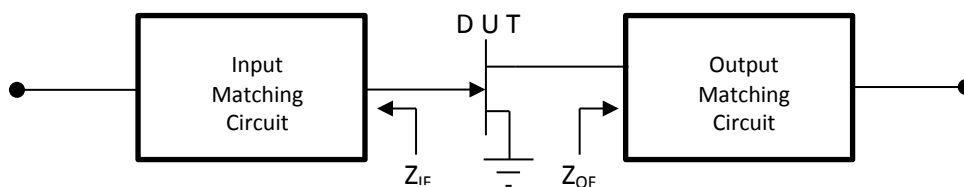
Note: Consult Integra Technologies Application Note 001 for information on how RF output power and pulse droop are measured for the ELM and Link 16 pulse trains.

**Table 4. Thermal Resistance (Case temperature = 85 °C unless otherwise stated)**

Parameter	Symbol	Typ	Units	Test Conditions
Peak Thermal Resistance, Channel to Case	$R_{TH}$	0.4	°C/W	$P_{DISS} = 269W$ Link 16 pulse conditions (444 x [7µs on, 6µs off], LTDC = 22.7%) $V_{DS} = 50V$

**Table 5. Test Fixture Source & Load Impedances (Case temperature = 25 °C unless otherwise stated)**

Frequency (MHz)	$Z_{IF}$	$Z_{OF}$	Units	Test Conditions
960	1.4 - j 0.4	1.9 - j 1.8	$\Omega$	$P_{OUT} = 500W$  Link 16 pulse conditions (444 x [7µs on, 6µs off], LTDC = 22.7%)  $V_{DS} = 50V, I_{DS} = 100mA$
1090	1.7 - j 0.0	2.0 - j 1.2	$\Omega$	
1215	1.7 + j 0.15	2.1 - j 0.6	$\Omega$	



**TYPICAL PERFORMANCE**

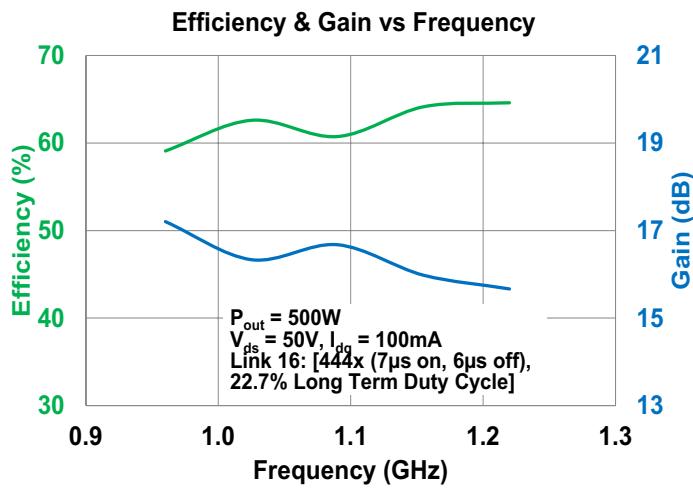


Figure 1

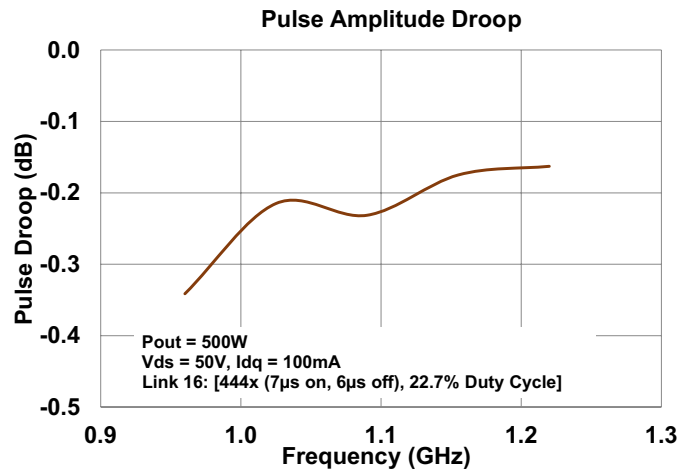


Figure 2

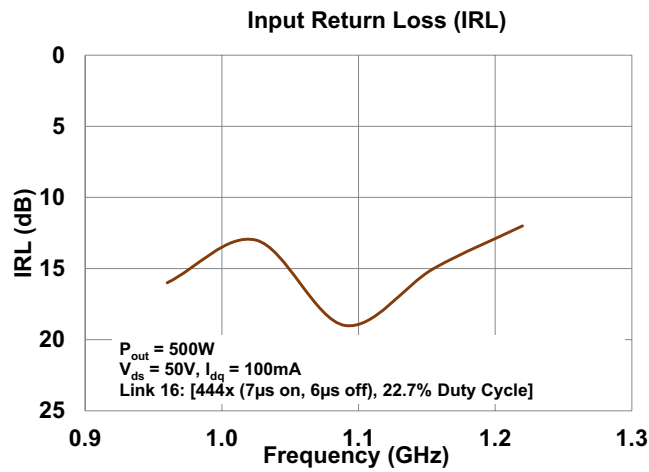
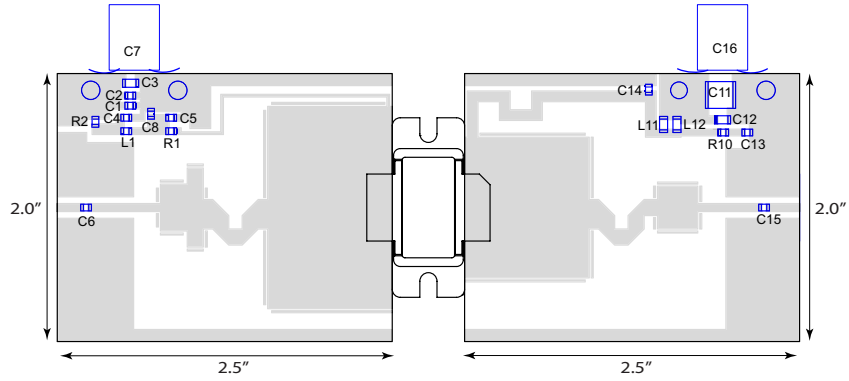


Figure 3

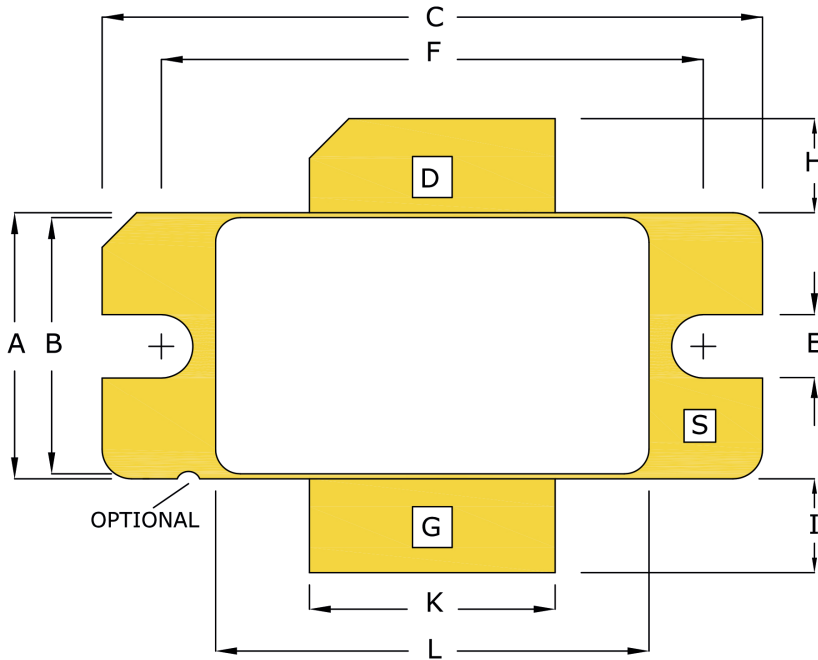
**TEST FIXTURE**



**Bill of Materials for IGN0912L500 Test Fixture**

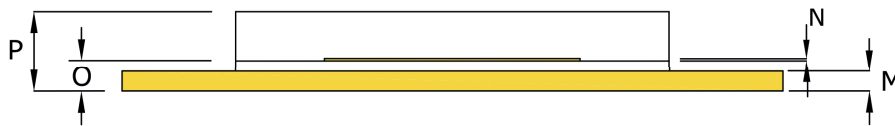
Designator	Description	Part Number
C1, C4, C13	CAP 0.1μF, 0805, 100V, X7R	08051C104K4T2A
C2, C5, C6, C14, C15	CAP 33pF, 0805	ATC600F330
C3, C12	CAP 1μF, 1206, 100V, X7R	12061C105K4T2A
C7, C16	CAP Electrolytic, 68μF, 63V (mounted external to pcb)	UPW1J680MPD
C8	CAP 1000pF, 0805, 100V	08051A102J4T2A
L1	Zero Ohm Resistor	
L11, L12	IND, FB, 33 OHM, 1206, 6A	BLM31PG330SN1L
R1, R10	RES, 15R0, 0805	ERJ-6ENF15R0V
R2	RES, 100 OHM, 0805	ERJ-6ENF1000V
PC Board Type	ROGERS RO4350B, 30mil, 1/1oz. Copper	

**PACKAGE PL95A1**



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.537	0.543	13.64	13.79
B	0.515	0.525	13.08	13.34
C	1.337	1.343	33.96	34.11
E	0.123	0.133	3.12	3.38
F	1.095	1.105	27.81	28.07
H	0.175	0.205	4.45	5.21
I	0.175	0.205	4.45	5.21
J	--	--	--	--
K	0.495	0.505	12.57	12.83
L	0.871	0.889	22.12	22.58
M	0.036	0.044	0.91	1.12
N	0.003	0.006	0.08	0.15
O	0.059	0.065	1.50	1.65
P	0.154	0.182	3.91	4.62

PIN SCHEDULE	
D	DRAIN
S	SOURCE
G	GATE



### ESD & MSL Rating

Parameter	Rating	Standard
ESD Human Body Model (HBM)	TBD	ESDA/JEDEC JS-001-2012
ESD Charged Device Model (CDM)	TBD	JEDEC JESD22-C101F
Moisture Sensitivity Level (MSL)	Unlimited Shelf Life	IPC/JEDEC J-STD-020

### RoHS Compliance

Integra Technologies, Inc declares that its GaN and LD MOS Transistor Products comply with EU Directive 2011/65/EU on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS2), as adopted by EU member states on January 2, 2013 and amended on March 31, 2015 by EU Directive 2015/863/EU.

### REACH Compliance

Integra Technologies supports EU Regulation number 1907/2006 concerning the Registration, Evaluation, Authorization, and Restriction of Chemicals (REACH) as these apply to Integra semiconductor products, development tools, and shipping packaging.

In support of the REACH regulation, Integra will:

- Inform customers and recipients of Integra product if they contain any substances that are of very high concern (SVHC) per the European Chemical Agency (ECHA) website.
- Notify ECHA if any Integra product that contains any SVHCs which exceed guidelines for REACH chemicals by weight per part number and for total content weight per year for all products produced in or imported to the European market.
- Cease shipments of product containing REACH Annex XIV substances until authorization has been obtained.
- Cease shipment of product containing REACH Annex XVII chemicals when restrictions apply.

Integra has evaluated its materials, BOMs, and product specifications and product and has determined that this transistor conforms to all REACH and SVHC regulations and guidelines. Integra has implemented actions and control programs that will assure continued compliance.

### Disclaimer

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**DEFINITIONS:**

**DATA SHEET STATUS**

Advanced Specification - This data sheet contains Advanced specifications.

Preliminary Specification - This data sheet contains specifications based on preliminary measurements and data.

Final Specification - This data sheet contains final product specifications.

**MAXIMUM RATINGS** Stress above one or more of the maximum ratings may cause permanent damage to the device. These are maximum ratings only operation of the device at these or at any other conditions above those given in the characteristics sections of the specification is not implied. Exposure to maximum values for extended periods of time may affect device reliability.

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